

Features

- ESD Protected Up To 2KV (HBM)
- Trench LV MOSFET Technology
- Operated At Low Logic Level Gate Drive
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

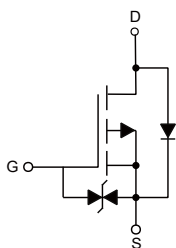
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 417°C/W Junction to Ambient (Note2)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	±12	V
Continuous Drain Current	I_D	$T_A=25^\circ\text{C}$	-0.66
		$T_A=100^\circ\text{C}$	-0.42
Pulsed Drain Current (Note3)	I_{DM}	-2.64	A
Total Power Dissipation (Note4)	P_D	0.3	W

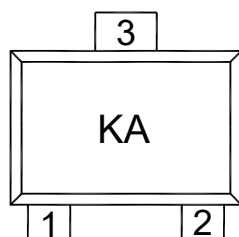
Note:

1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.

Internal Structure and Marking Code

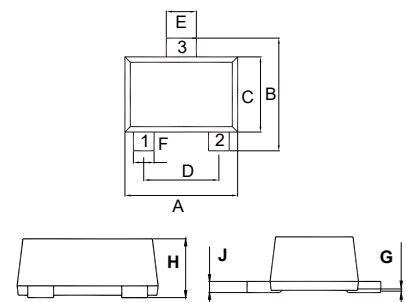


1. GATE
2. SOURCE
3. DRAIN



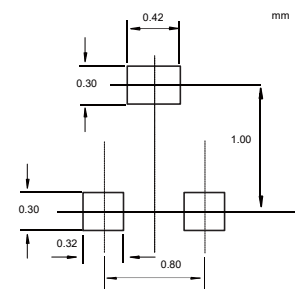
P-Channel MOSFET

SOT-723



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.043	0.051	1.10	1.30	
B	0.043	0.051	1.10	1.30	
C	0.028	0.035	0.70	0.90	
D	0.031		0.80		TYP.
E	0.009	0.017	0.22	0.42	
F	0.005	0.013	0.12	0.32	
G	0.000	0.002	0.00	0.05	
H	0.017	0.021	0.43	0.54	
J	0.003	0.006	0.08	0.15	

Suggested Solder Pad Layout



ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-20			V
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.35	-0.64	-1.1	V
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 10V, V_{DS}=0V$			± 10	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20V, V_{GS}=0V$			-1	μA
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-4.5V, I_D=-500mA$		0.62	0.85	Ω
		$V_{GS}=-2.5V, I_D=-300mA$		0.89	1.2	
		$V_{GS}=-1.8V, I_D=-200mA$		1.35	2	
Forward Transconductance	g_{FS}	$V_{DS}=-5V, I_D=-600mA$		1		S
Gate Resistance	R_g	f=1 MHz, Open drain		31		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				-0.66	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=-500mA$			-1.2	V
Reverse Recovery Time	t_{rr}	$I_F=-0.3A, dI_F/dt=100A/\mu s$		8.6		ns
Reverse Recovery Charge	Q_{rr}			2.5		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=-16V, V_{GS}=0V, f=1MHz$		35		μF
Output Capacitance	C_{oss}			10.4		
Reverse Transfer Capacitance	C_{rss}			5.7		
Total Gate Charge	Q_g	$V_{DS}=-10V, V_{GS}=-4.5V, I_D=-1A$		1.12		nC
Gate-Source Charge	Q_{gs}			0.36		
Gate-Drain Charge	Q_{gd}			0.21		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=-10V, V_{GS}=-4.5V,$ $R_G=10\Omega, I_D=-0.5A$		6.1		ns
Turn-On Rise Time	t_r			5.5		
Turn-Off Delay Time	$t_{d(off)}$			10.7		
Turn-Off Fall Time	t_f			5.6		

Curve Characteristics

Fig.1 - Typical Output Characteristics

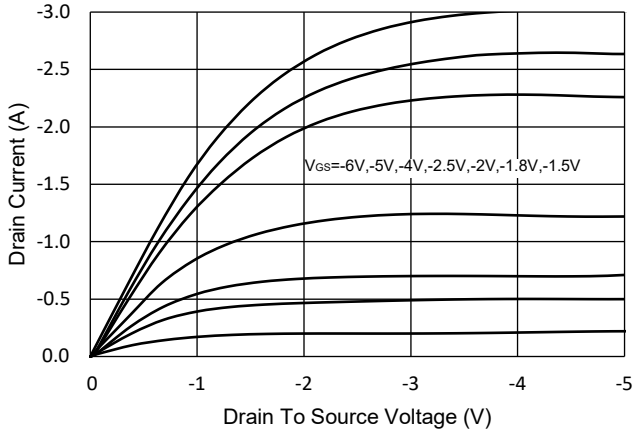


Fig.2 - Transfer Characteristic

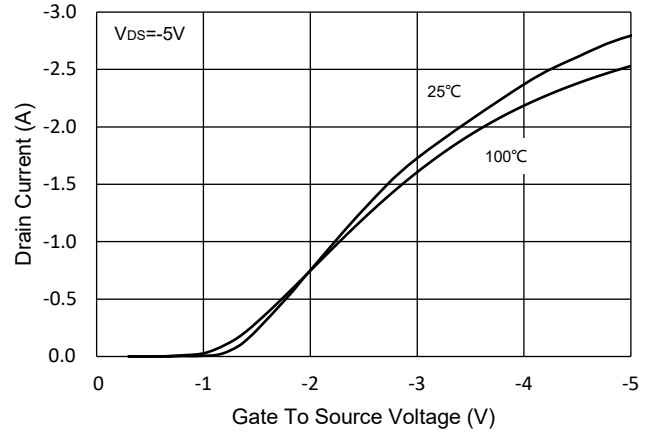


Fig.3 - $R_{DS(ON)}$ - V_{GS}

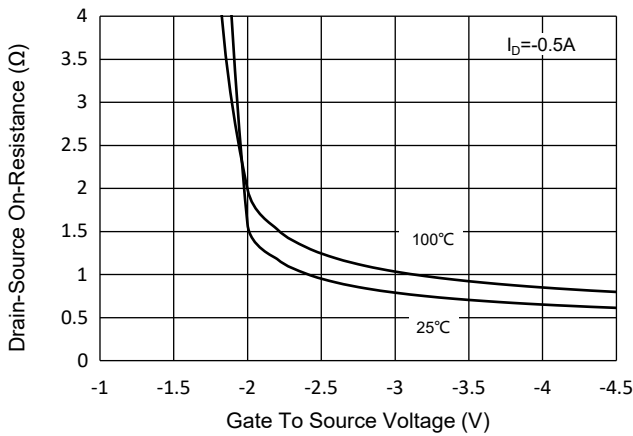


Fig.4 - $R_{DS(ON)}$ - I_D

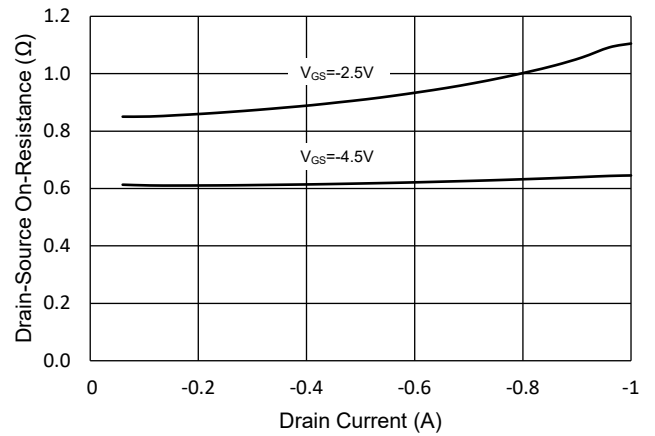


Fig.5 - Capacitance Characteristics

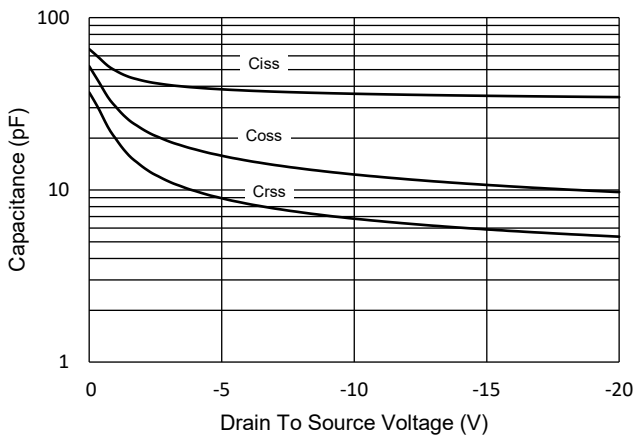
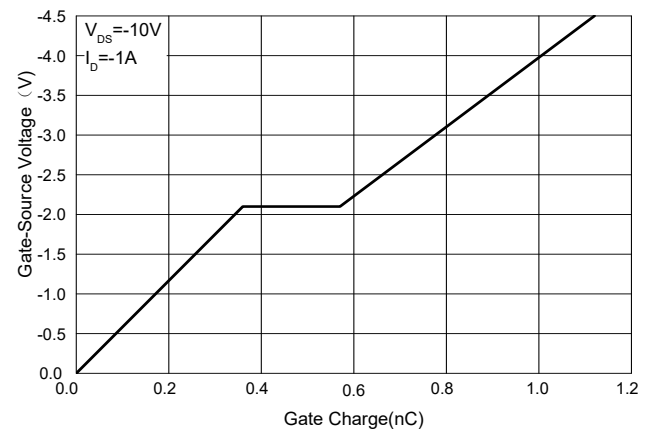


Fig.6 - Gate Charge



Curve Characteristics

Fig.7 - Normalized Threshold Voltage

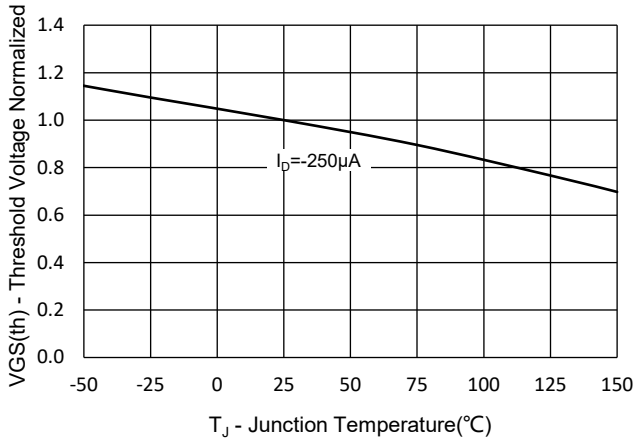


Fig.8 - Normalized On Resistance Characteristics

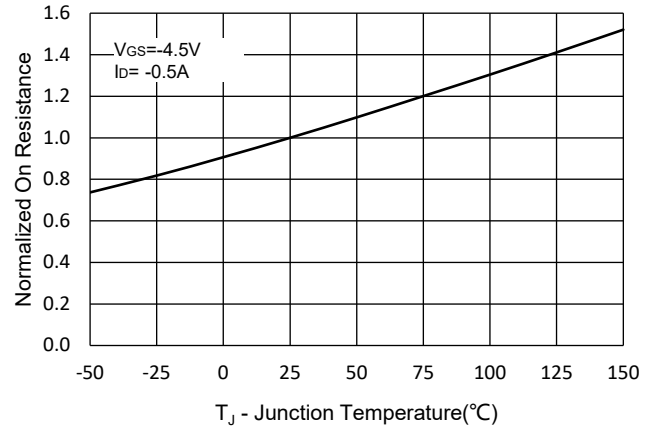


Fig.9 - I_S - V_{SD}

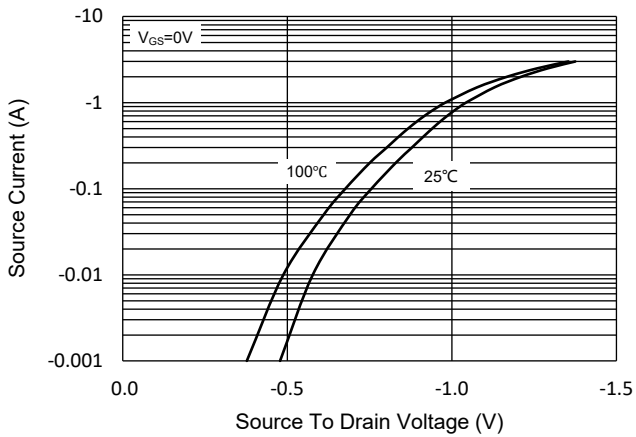


Fig.10 - Drain Current

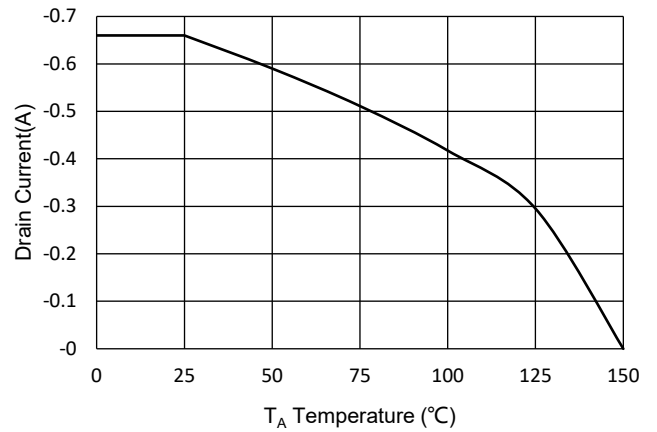
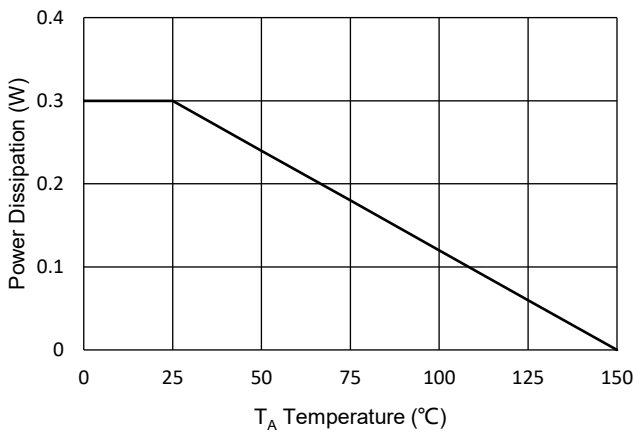


Fig.11 - PD Dissipation



Curve Characteristics

Fig.12 - Safe Operation Area

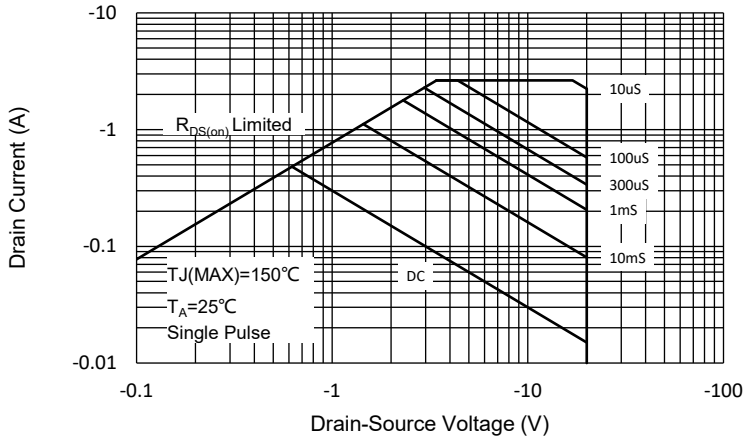
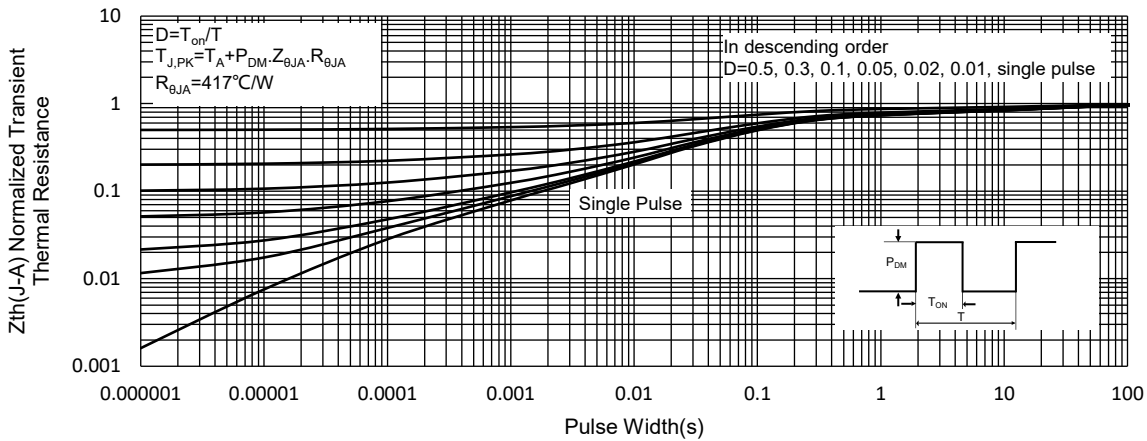


Fig.13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel:8Kpcs/Reel

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